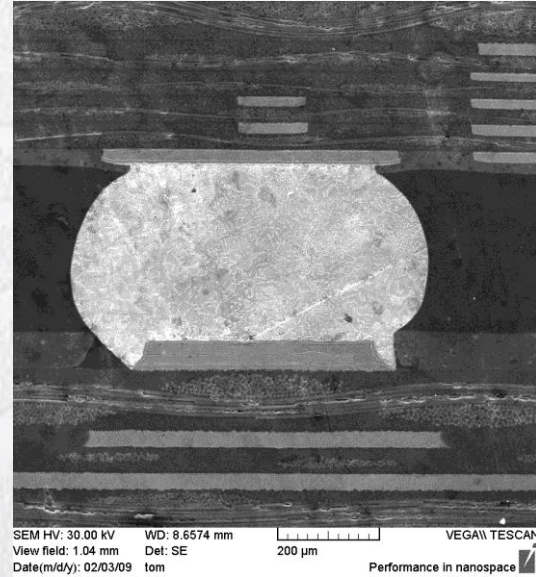
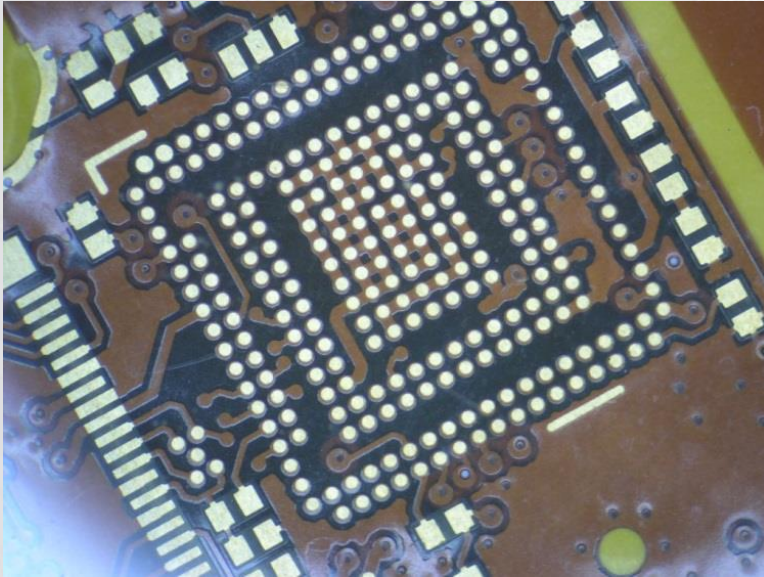


TechniPad ENEPIG

Solderability

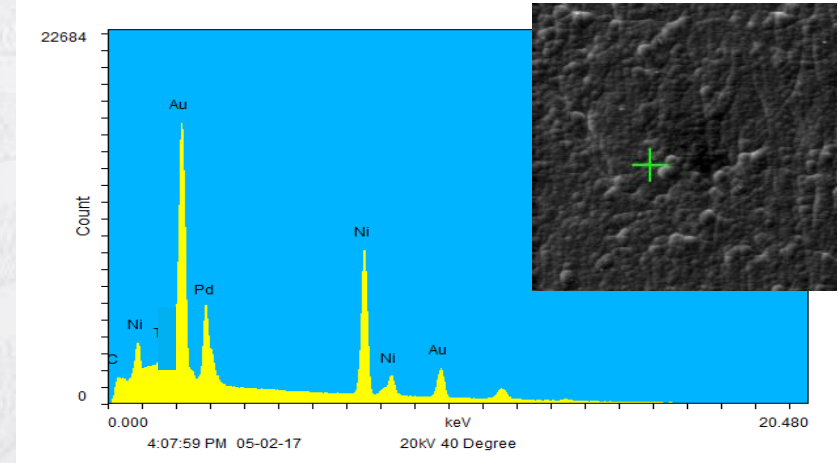
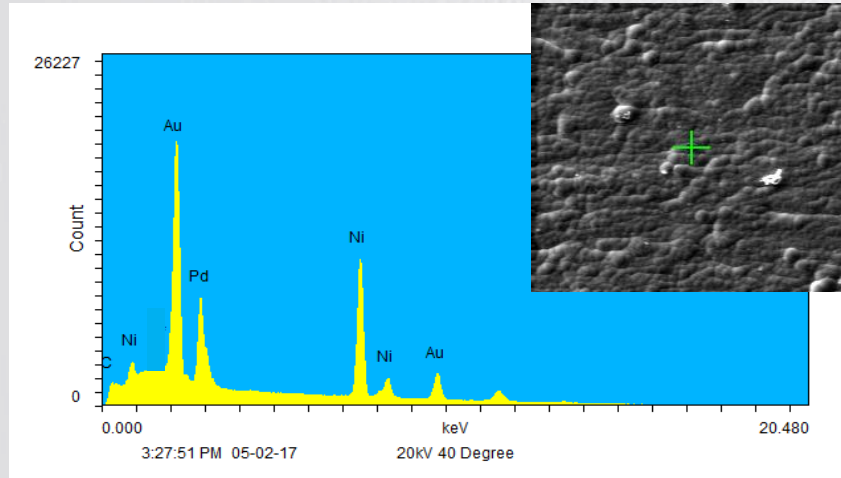


EDS ENEPIG(1.7 micro inch Pd) After 4 Hour Bake

Excellent Protection Even With Thin Pd:
No Difference in Surface Analysis After Bake

As Plated

4 Hour 175 °C



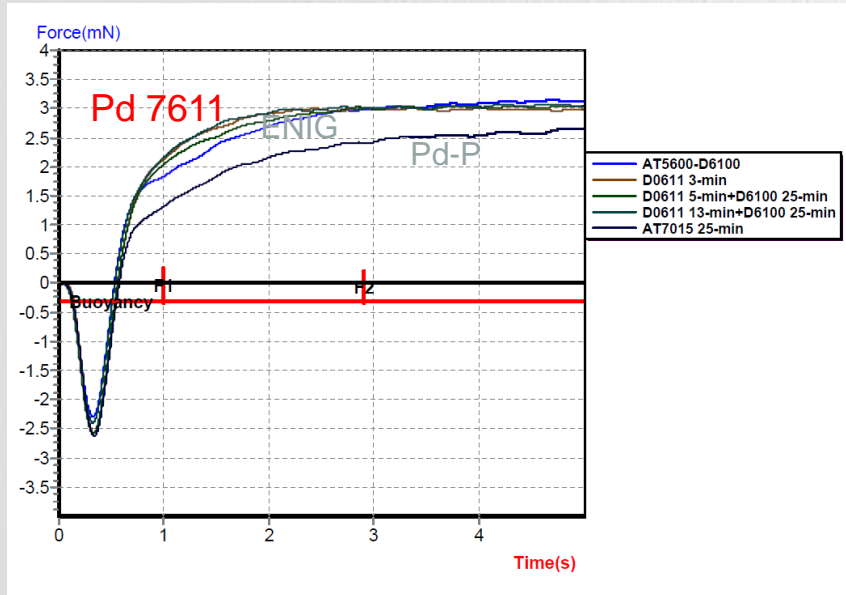
Elements:	WT%	AT%	K_A	K_F	K_Z	Intensity	P/bkg
PdL	25.36	25.52	0.711	1	0.997	323.109	2.1
NiK	26.51	48.33	0.949	1.027	1.155	748.725	11.8
AuL	48.13	26.16	0.995	1	0.874	161.992	3.4

Elements:	WT%	AT%	K_A	K_F	K_Z	Intensity	P/bkg
PdL	21.84	22.31	0.696	1	0.999	276.006	1.8
NiK	26.59	49.23	0.949	1.029	1.159	762.853	11.7
AuL	51.56	28.45	0.995	1	0.878	176.117	3.7

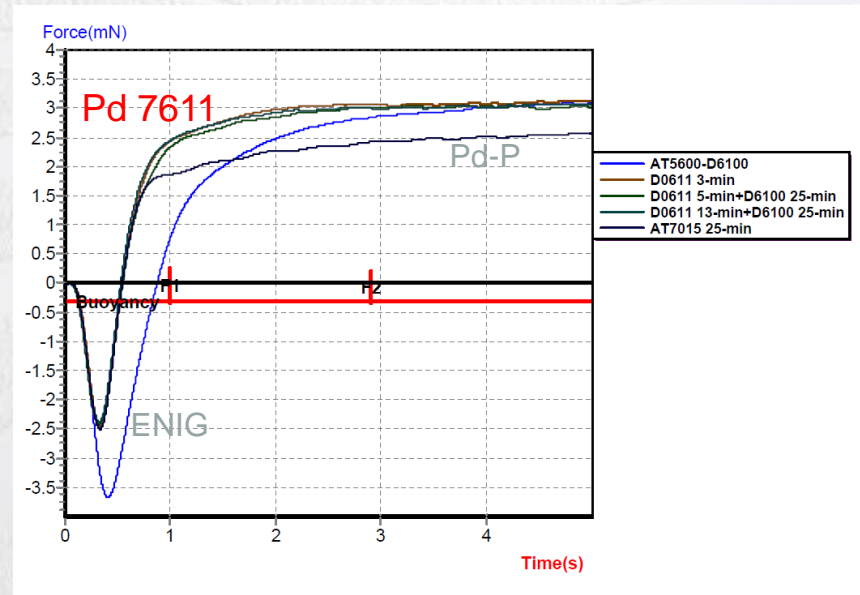
TechniPad Pd 7611: Wetting Balance Results

Pure Pd, Vs. Pd-P, Vs. ENIG

As Plated

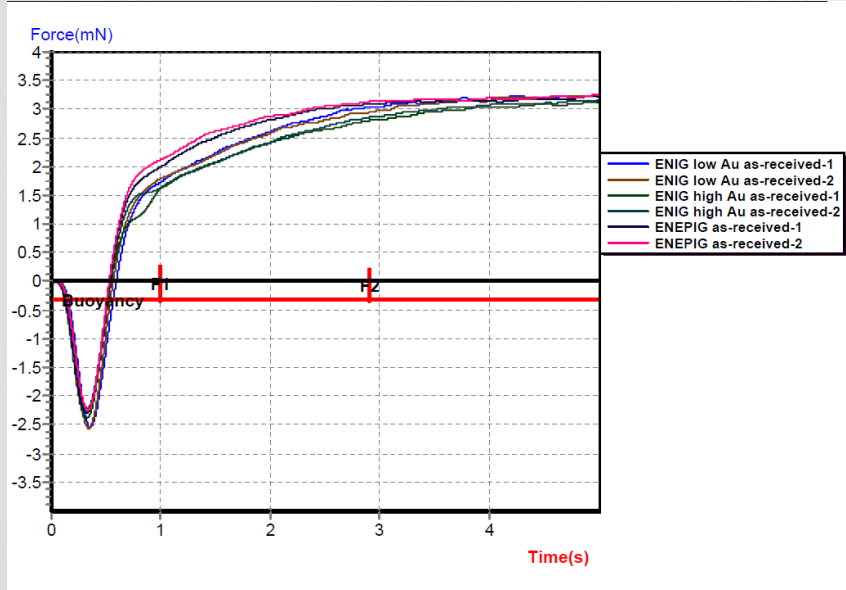


2 Hour Bake 155C

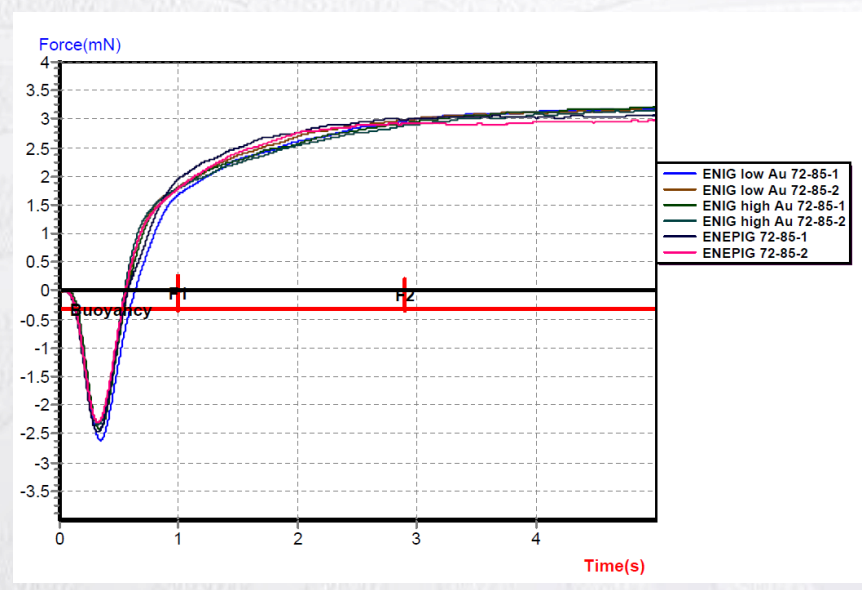


Wetting Balance Per J-STD-003C

As Plated

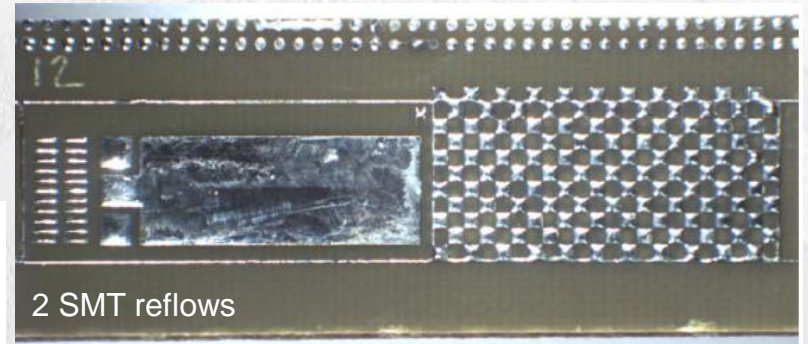
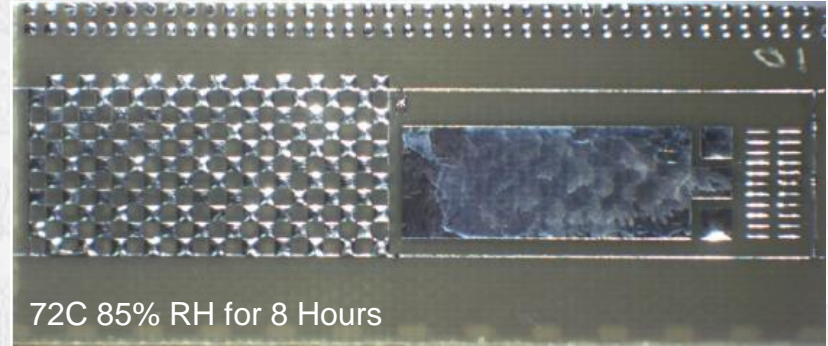


After 72C 85% RH 8 Hours



Independent Lab: Dip & Look Per J-STD-003C

- TechniPad ENEPIG Thickness: 4.5 Pd, 1.9 Au
- Aging:
 - 8 hours 72 °C, 85% RH & 1 hour 105 °C
 - 2 SMT reflows in air
- 10 sec dip 235 ± 5 C
- Results:



Serial Number		9	10	11	12
Solderability Surface per J-STD-003C	Accept	X	X	X	X
	Reject				

THE SOLUTION: TechniPad ENIG & ENEPIG

- **Outstanding Assembly Performance**
 - Flat EN = No black pad/corrosion products on EN Surface
 - Proprietary immersion gold process with almost no Ni removal
 - Thin intermetallic
- **Lowest Operating Cost**
- **Solves ENIG Process Issues**
- **All Interconnect Applications**
 - Low contact & good wear resistance
 - Wire bondable
 - Solderable

